## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of

HONG et al.

Atty. Ref.: 2826-9

Serial No. unknown

Group:

Filed: January 17, 2002

Examiner:

10-15-03

For: METHOD AND APPARATUS FOR CUTTING A MULTI-LAYER SUBSTRATE

BY DUAL LASER IRRADIATION

: \* \* \* \* \* \* \* \*

January 17, 2002

Assistant Commissioner for Patents Washington, DC 20231

Sir:

## PRELIMINARY AMENDMENT

In order to place the above-identified application in better condition for examination, please amend the application as follows:

## **IN THE CLAIMS**

Please substitute the following amended claims for corresponding claims previously presented. A copy of the amended claims showing current revisions is attached.